WHAT IS CLAIMED IS:

1. A dicing method, comprising:

an intermediate dicing step of forming intermediate dicing grooves along predetermined cutting lines on one side of a base plate, the depth of the intermediate dicing grooves being less than the depth of the base plate, and forming inclined surfaces on both sides of the opening of each intermediate dicing groove;

a bonding step of bonding a tacky-adhesive tape to the surface of the base plate where the intermediate dicing grooves are formed; and

a split-dicing step of forming cutting dicing grooves, on a side opposite to the one side of the base plate where the intermediate dicing grooves are formed, so as to be extended along the intermediate dicing grooves and so as to reach the intermediate dicing grooves, whereby the base plate may be split along the cutting lines.

2. The dicing method according to claim 1, wherein, in the intermediate dicing step, tapered grooves are formed on one side of the base plate along the predetermined cutting lines so as to have inclined surfaces on both sides of each tapered groove, and thereafter, the intermediate dicing grooves are provided.

3. The dicing method according to claim 1, further comprising:

the bonding step succeeding the intermediate dicing step, and defining a second bonding step;

before the intermediate dicing step, a first bonding step of bonding a first tacky-adhesive tape to the opening on one side of a frame-shaped jig for fixing the base plate to the dicing apparatus; and

securing the other-side surface of the base plate to the first tacky-adhesive tape;

wherein the tack-adhesive tape bonded in the second bonding step is a second tacky-adhesive tape; and

wherein the second tacky-adhesive tape is bonded to the surface of the base plate where the intermediate dicing grooves are formed, and the first tacky-adhesive tape is released.

4. The dicing method according to claim 1, wherein the base plate is a glass plate.

5. The dicing method according to claim 4, wherein the thickness of the glass plate is in the range of 0.5 mm to 2 mm.

6. A dicing method according to claim 4, further comprising disposing an anti-reflection film on the one side of the glass plate.

7. The dicing method according to claim 6, further comprising:

after the bonding step, irradiating light to the glass plate, and

detecting the positions of the intermediate dicing grooves by using light reflected from or transmitted through the glass plate.

8. A cover glass processed by the dicing method defined in claim 1.

9. A liquid crystal panel in which an electro-optical material is sealed between a pair of substrates, wherein the cover glass defined in claim 8 is attached to the substrates.

10. A liquid crystal projector, wherein the liquid crystal panel defined in claim 9 is used.

11. A sold-state image sensing device comprising a casing having an opening, a sold-state image sensing device accommodated in the casing, and the cover glass defined in claim 8 arranged in opposition to the sold-state image sensing device to close the opening of the casing.

12. A digital image recognition device having the sold-state sensing device defined in claim 11.

13. A dicing method, comprising:

an intermediate dicing step of forming intermediate dicing grooves along predetermined cutting lines on one side of a base plate, depth of the intermediate dicing grooves being less than the depth of the base plate:

a bonding step of bonding a tacky-adhesive tape to a surface of the base plate where the intermediate dicing grooves are formed:

a tapered groove formation step of forming tapered grooves on the side of the base plate opposite to the side where the intermediate dicing grooves are formed, along the intermediate dicing grooves, so as to have inclined surfaces on both sides of each tapered groove; and a split-dicing step of forming cutting-dicing grooves substantially along centers of the tapered grooves, the cutting-dicing grooves having a width smaller than the tapered grooves and reaching the intermediate dicing grooves, whereby the base plate is split along the cutting lines.

14. The dicing method according to claim 13, further comprising:

before the intermediate dicing step, a first bonding step of:

bonding a first tacky-adhesive tape to the opening on one side of a frame-shaped jig,

fixing the base plate to the dicing apparatus by securing the other-side surface of the base plate to the first tacky-adhesive tape,

the bonding step succeeding the intermediate dicing step defining a second bonding step and the tacky-adhesive tape of the second bonding step defining a second tacky-adhesive tape;

in the second bonding step, bonding the second tacky-adhesive tape so as to cover the opening on the other side of the jig and where the intermediate dicing grooves are formed; and then

releasing the first tacky-adhesive tape.

15. The dicing method according to claim 13, wherein the base plate is a glass plate.

16. The dicing method according to claim 15, wherein the thickness of the glass plate is in the range of 0.5 mm to 2 mm.

17. The dicing method according to claim 15, further comprising disposing an anti-reflection film on the one side of the glass plate.